


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMS/16/9620	
1.3 Title of PCN	Product Change Notification on the Standardization of the backside coating thickness for wafer level CSP	
1.4 Product Category	See product list	
1.5 Issue date	2016-02-22	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Andrea Mario ONETTI
2.1.2 Marketing Manager	Lionel GRILLO,Wing-Sze LEE
2.1.3 Quality Manager	Jean-Marc BUGNARD,Giuseppe LISI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Backside finish modification except for wafer for sale: change in deposition material type/nature or final thickness	ST Shenzen

4. Description of change

	Old	New
4.1 Description	Back coating thickness is 50µm or 25µm depending on the product	Back coating thickness will be standardized to 25µm
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on form, fit, function, reliability, or processability	

5. Reason / motivation for change

5.1 Motivation	The standardization of the material used for package assembly will secure the purchasing of the direct material and improve the service to ST Customers for the affected package.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Full traceability will be ensured thanks to traceability code and Bulk Id.
------------------------	--

7. Timing / schedule

7.1 Date of qualification results	2016-01-15
7.2 Intended start of delivery	2016-03-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	qual report backcoating 25.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2016-02-22

9. Attachments (additional documentations)

9620PpPrdtLst.pdf
qual report backcoating 25.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
2460895	GG25LAJ	
2460896	GG25LJ	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics – All rights reserved